

## CD4063B Types

### CMOS 4-Bit Magnitude Comparator

#### High Voltage Types (20-Volt Rating)

The RCA-CD4063B is a 4-bit magnitude comparator designed for use in computer and logic applications that require the comparison of two 4-bit words. This logic circuit determines whether one 4-bit word (Binary or BCD) is "less than", "equal to", or "greater than" a second 4-bit word.

The CD4063B has eight comparing inputs ( $A_3, B_3$ , through  $A_0, B_0$ ), three outputs ( $A < B, A = B, A > B$ ) and three cascading inputs ( $A < B, A = B, A > B$ ) that permit systems designers to expand the comparator function to 8, 12, 16 . . . 4N bits. When a single CD4063B is used, the cascading inputs are connected as follows: ( $A < B$ ) = low, ( $A = B$ ) = high, ( $A > B$ ) = low.

For words longer than 4 bits, CD4063B devices may be cascaded by connecting the outputs of the less-significant comparator to the corresponding cascading inputs of the more-significant comparator. Cascading inputs ( $A < B, A = B$ , and  $A > B$ ) on the least significant comparator are connected to a low, a high, and a low level, respectively.

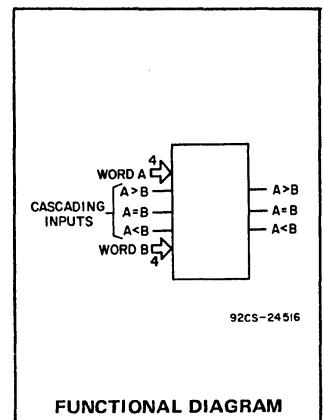
The CD4063B types are supplied in 16-lead hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic package (E suffix), 16-lead ceramic flat package (K suffix), and in chip form (H suffix). This device is pin-compatible with the standard 7485 TTL type.

#### Features:

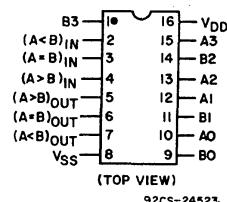
- Expansion to 8, 12, 16 . . . 4N bits by cascading units
- Medium-speed operation:  
compares two 4-bit words  
in 250 ns (typ.) at 10 V
- 100% tested for quiescent current at 20 V
- Standardized symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Maximum input current of 1  $\mu$ A at 18 V  
over full package temperature range;  
100 nA at 18 V and 25°C
- Noise margin (full package temperature range)  
range) = 1 V at  $V_{DD} = 5$  V  
2 V at  $V_{DD} = 10$  V  
2.5 V at  $V_{DD} = 15$  V
- Meets all requirements of JEDEC Tentative Standard No. 13A, "Standard Specifications for Description of 'B' Series CMOS Devices"

#### Applications:

- Servo motor controls ■ Process controllers



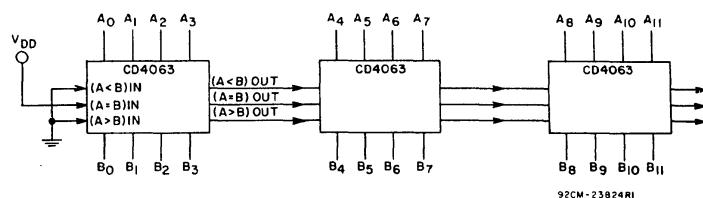
FUNCTIONAL DIAGRAM



TERMINAL ASSIGNMENT

#### MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ ) (Voltages referenced to $V_{SS}$ Terminal)	. . . . .	-0.5 to +20 V
INPUT VOLTAGE RANGE, ALL INPUTS	. . . . .	-0.5 to $V_{DD} + 0.5$ V
DC INPUT CURRENT, ANY ONE INPUT	. . . . .	$\pm 10$ mA
POWER DISSIPATION PER PACKAGE ( $P_D$ ):		
For $T_A = -40$ to $+60^\circ\text{C}$ (PACKAGE TYPE E)	. . . . .	500 mW
For $T_A = +60$ to $+85^\circ\text{C}$ (PACKAGE TYPE E)	. . . . .	Derate Linearly at 12 mW/ $^\circ\text{C}$ to 200 mW
For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPES D, F, K)	. . . . .	500 mW
For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPES D, F, K)	. . . . .	Derate Linearly at 12 mW/ $^\circ\text{C}$ to 200 mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR FOR $T_A = \text{FULL PACKAGE TEMPERATURE RANGE}$ (All Package Types)	. . . . .	100 mW
OPERATING-TEMPERATURE RANGE ( $T_A$ ):		
PACKAGE TYPES D, F, K, H	. . . . .	-55 to $+125^\circ\text{C}$
PACKAGE TYPE E	. . . . .	-40 to $+85^\circ\text{C}$
STORAGE TEMPERATURE RANGE ( $T_{stg}$ )	. . . . .	-65 to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING): At distance $1/16 \pm 1/32$ inch (1.59 $\pm$ 0.79 mm) from case for 10 s max.	. . . . .	+265°C



$$t_p \text{ TOTAL} = t_p \text{ (COMPARE)} + 2 \times t_p \text{ (CASCADE)} \text{, AT } V_{DD} = 10V \\ (3 \text{ STAGES})$$

$$= 250 + (2 \times 200) = 650 \text{ ns (TYP.)}$$

Fig. 1 — Typical speed characteristics of a 12-bit comparator.

#### RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	Min.	Max.	
Supply-Voltage Range (For $T_A = \text{Full Package-}$ Temperature Range)	3	18	V

## CD4063B Types

### STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)						UNITS	
				Values at -55, +25, +125 Apply to D, F, K, H Packages				+25			
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	-55	-40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, IDD Max.	—	0,5	5	5	5	150	150	—	0.04	5	μA
	—	0,10	10	10	10	300	300	—	0.04	10	
	—	0,15	15	20	20	600	600	—	0.04	20	
	—	0,20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current IOL Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, IOH Min.	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	mA
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
Output Voltage: Low-Level, VOL Max.	—	0,5	5	0.05				—	0	0.05	V
	—	0,10	10	0.05				—	0	0.05	
	—	0,15	15	0.05				—	0	0.05	
Output Voltage: High-Level, VOH Min.	—	0,5	5	4.95				4.95	5	—	V
	—	0,10	10	9.95				9.95	10	—	
	—	0,15	15	14.95				14.95	15	—	
Input Low Voltage, VIL Max.	0.5, 4.5	—	5	1.5				—	—	1.5	V
	1, 9	—	10	3				—	—	3	
	1.5, 13.5	—	15	4				—	—	4	
Input High Voltage, VH Min.	0.5, 4.5	—	5	3.5				3.5	—	—	V
	1, 9	—	10	7				7	—	—	
	1.5, 13.5	—	15	11				11	—	—	
Input Current IIN Max.	—	0,18	18	±0.1	±0.1	±1	±1	—	±10 <sup>-5</sup>	±0.1	μA

TRUTH TABLE

INPUTS					OUTPUTS				
COMPARING				CASCAADING					
A <sub>3</sub> , B <sub>3</sub>	A <sub>2</sub> , B <sub>2</sub>	A <sub>1</sub> , B <sub>1</sub>	A <sub>0</sub> , B <sub>0</sub>	A < B	A = B	A > B	A < B	A = B	A > B
A <sub>3</sub> > B <sub>3</sub>	X	X	X	X	X	X	0	0	1
A <sub>3</sub> = B <sub>3</sub>	A <sub>2</sub> > B <sub>2</sub>	X	X	X	X	X	0	0	1
A <sub>3</sub> = B <sub>3</sub>	A <sub>2</sub> = B <sub>2</sub>	A <sub>1</sub> > B <sub>1</sub>	X	X	X	X	0	0	1
A <sub>3</sub> = B <sub>3</sub>	A <sub>2</sub> = B <sub>2</sub>	A <sub>1</sub> = B <sub>1</sub>	A <sub>0</sub> > B <sub>0</sub>	X	X	X	0	0	1
A <sub>3</sub> = B <sub>3</sub>	A <sub>2</sub> = B <sub>2</sub>	A <sub>1</sub> = B <sub>1</sub>	A <sub>0</sub> = B <sub>0</sub>	0	0	1	0	0	1
A <sub>3</sub> = B <sub>3</sub>	A <sub>2</sub> = B <sub>2</sub>	A <sub>1</sub> = B <sub>1</sub>	A <sub>0</sub> = B <sub>0</sub>	0	1	0	0	1	0
A <sub>3</sub> = B <sub>3</sub>	A <sub>2</sub> = B <sub>2</sub>	A <sub>1</sub> = B <sub>1</sub>	A <sub>0</sub> = B <sub>0</sub>	1	0	0	1	0	0
A <sub>3</sub> = B <sub>3</sub>	A <sub>2</sub> = B <sub>2</sub>	A <sub>1</sub> = B <sub>1</sub>	A <sub>0</sub> < B <sub>0</sub>	X	X	X	1	0	0
A <sub>3</sub> = B <sub>3</sub>	A <sub>2</sub> = B <sub>2</sub>	A <sub>1</sub> < B <sub>1</sub>	X	X	X	X	1	0	0
A <sub>3</sub> = B <sub>3</sub>	A <sub>2</sub> < B <sub>2</sub>	X	X	X	X	X	1	0	0
A <sub>3</sub> < B <sub>3</sub>	X	X	X	X	X	X	1	0	0

X = Don't Care

Logic 1 ≡ High Level

Logic 0 ≡ Low Level

## CD4063B Types

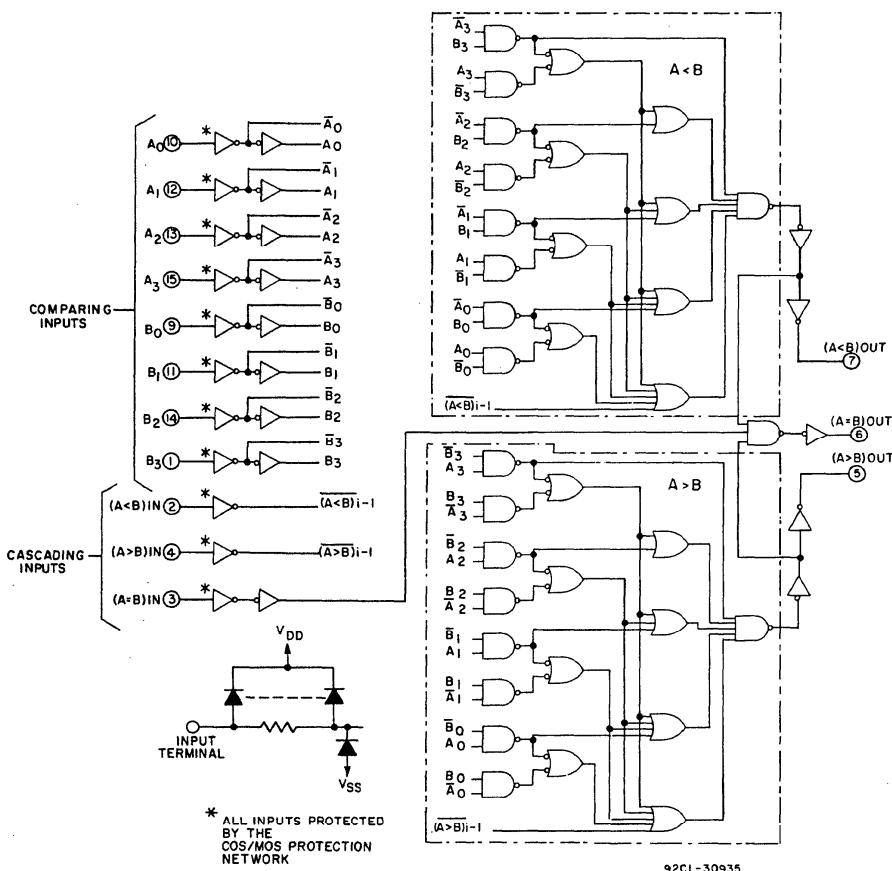


Fig. 2 – Logic diagram for CD4063B.

### DYNAMIC ELECTRICAL CHARACTERISTICS

At  $T_A = 25^\circ C$ ; Input  $t_r$ ,  $t_f = 20\text{ ns}$ ,  $C_L = 50\text{ pF}$ ,  $R_L = 200k\Omega$

CHARACTERISTIC	TEST CONDITIONS	ALL TYPES LIMITS			UNITS
		$V_{DD}$ Volts	Typ.	Max.	
Propagation Delay Time: Comparing Inputs to Outputs, $t_{PHL}$ , $t_{PLH}$		5	625	1250	ns
		10	250	500	
		15	175	350	
Cascading Inputs to Outputs, $t_{PHL}$ , $t_{PLH}$		5	500	1000	ns
		10	200	400	
		15	140	280	
Transition Time, $t_{THL}$ , $t_{TLH}$		5	100	200	ns
		10	50	100	
		15	40	80	
Input Capacitance, $C_{IN}$	Any Input	5	7.5	pF	

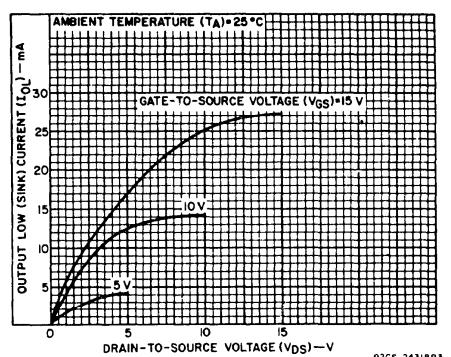


Fig. 3 – Typical output low (sink) current characteristics.

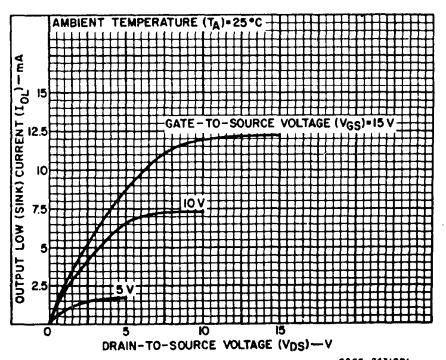


Fig. 4 – Minimum output low (sink) current characteristics.

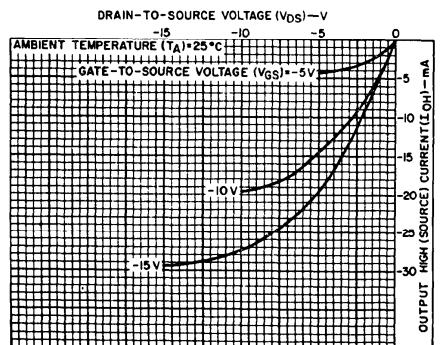


Fig. 5 – Typical output high (source) current characteristics.

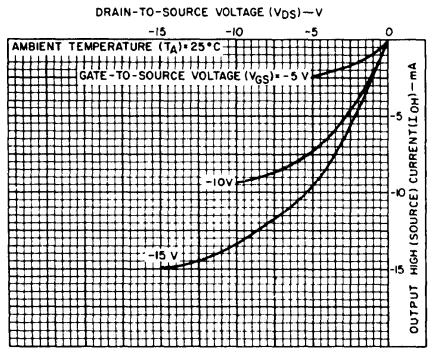
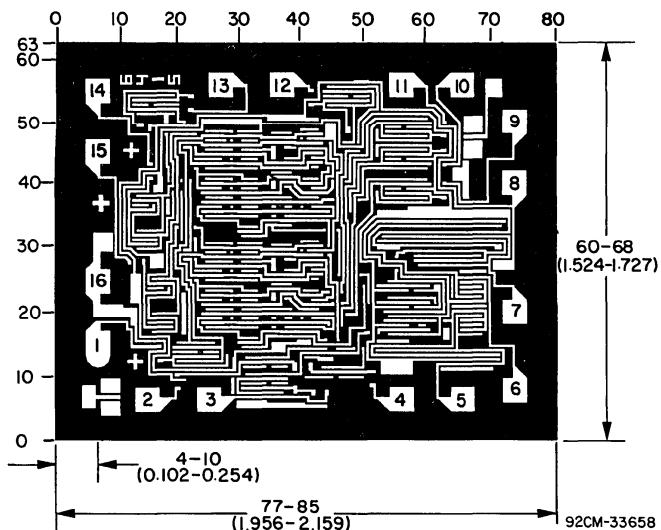
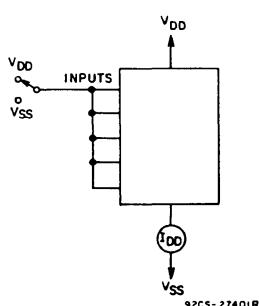
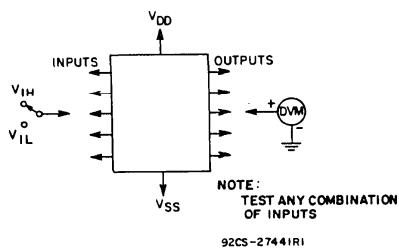
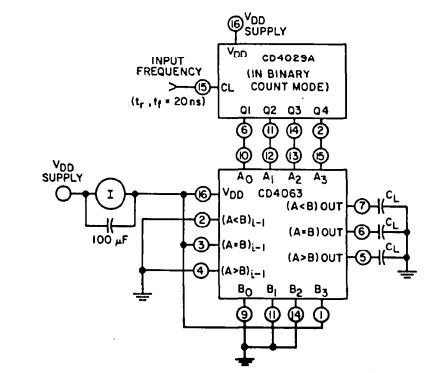
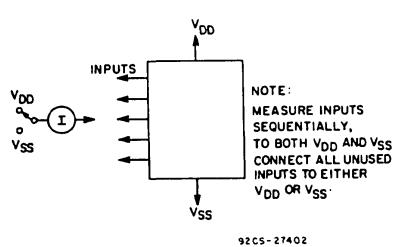
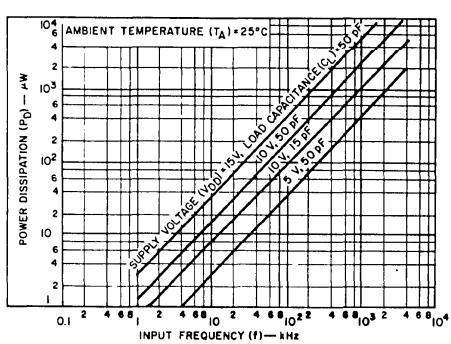
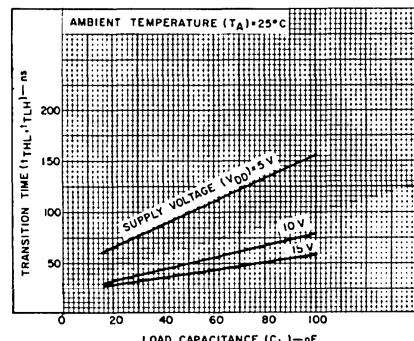
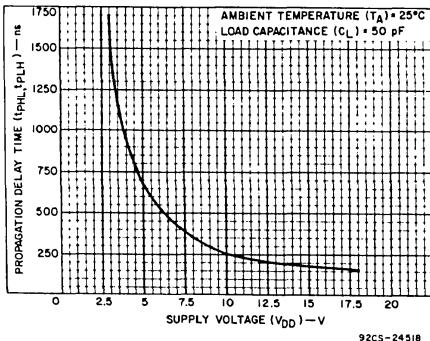
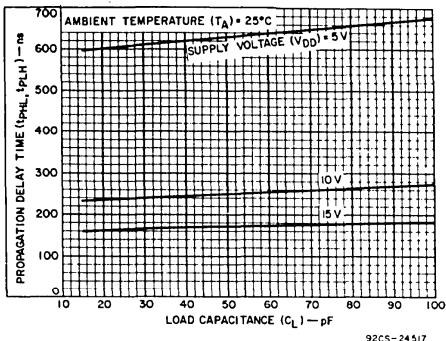


Fig. 6 – Minimum output high (source) current characteristics.

## CD4063B Types



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).

The photographs and dimensions of each CMOS chip represent a chip when it is part of the wafer. When the wafer is separated into individual chips, the angle of cleavage may vary with respect to the chip face for different chips. The actual dimensions of the isolated chip, therefore, may differ slightly from the nominal dimensions shown. The user should consider a tolerance of -3 mils to +16 mils applicable to the nominal dimensions shown.